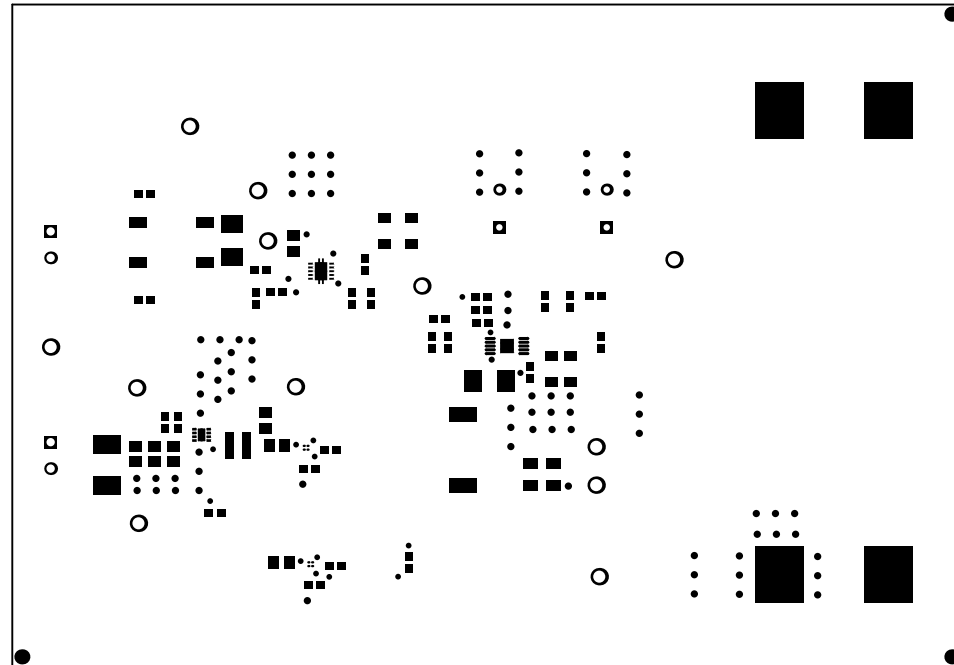
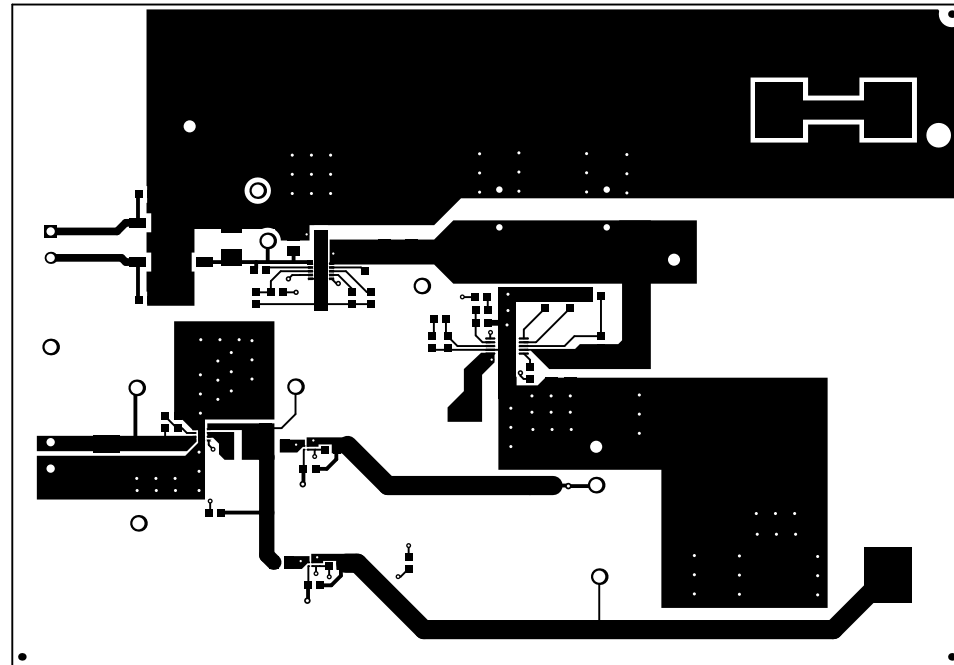


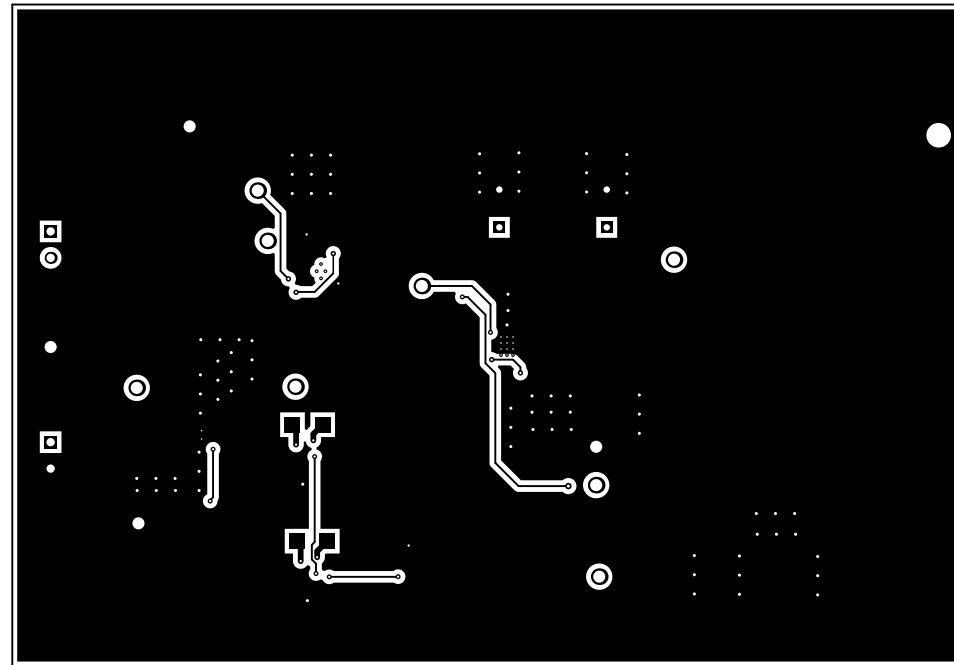
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01574	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01574		
PLOT NAME = Top Overlay	GENERATED : 12/15/2017 12:21:11 AM	TEXAS INSTRUMENTS	



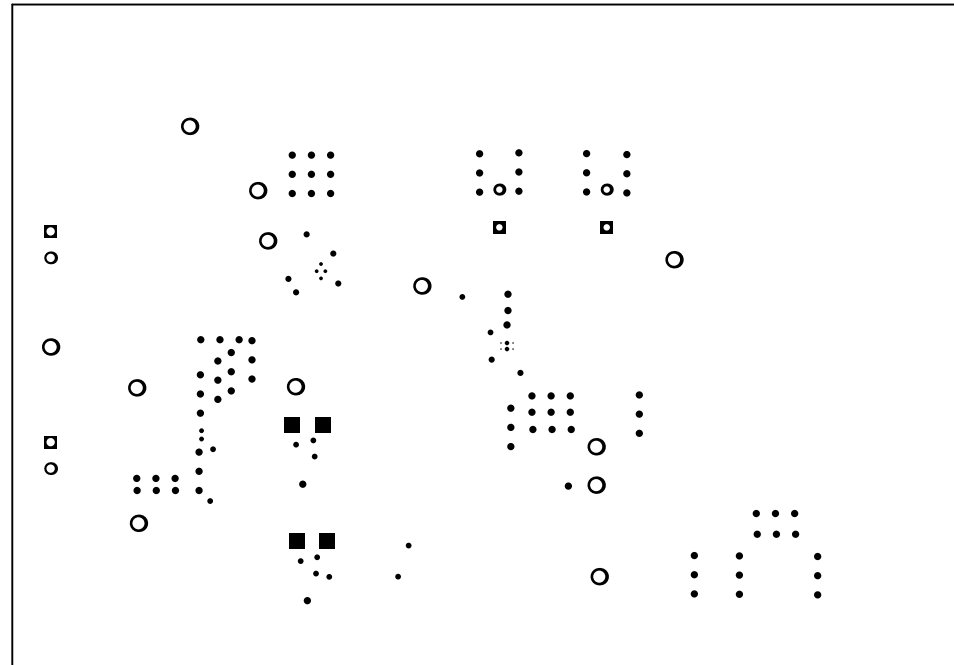
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01574	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01574		
PLOT NAME = Top Solder Mask	GENERATED : 12/15/2017 12:21:12 AM	TEXAS INSTRUMENTS	



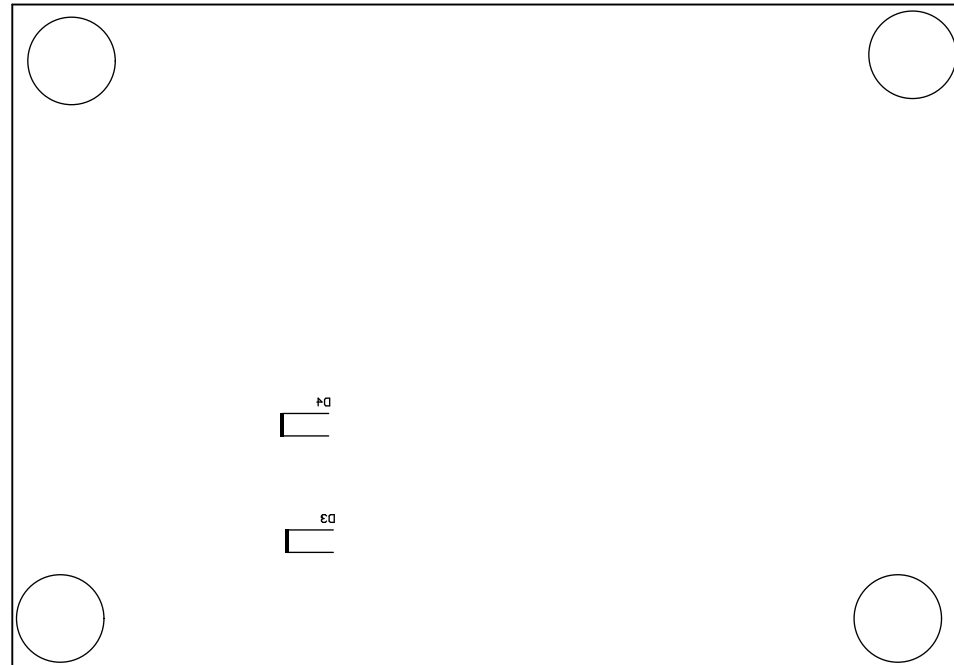
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01574	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01574		
PLOT NAME = Top Layer	GENERATED : 12/15/2017 12:21:13 AM	TEXAS INSTRUMENTS	



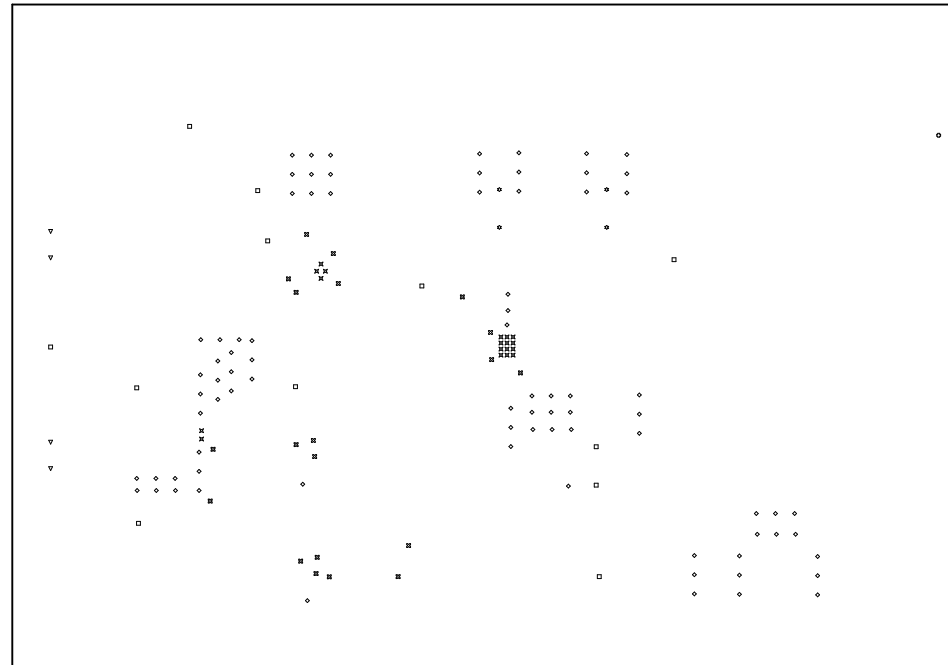
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01574	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01574		
PLOT NAME = Bottom Layer	GENERATED : 12/15/2017 12:21:14 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01574	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01574		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/15/2017 12:21:16 AM	TEXAS INSTRUMENTS	

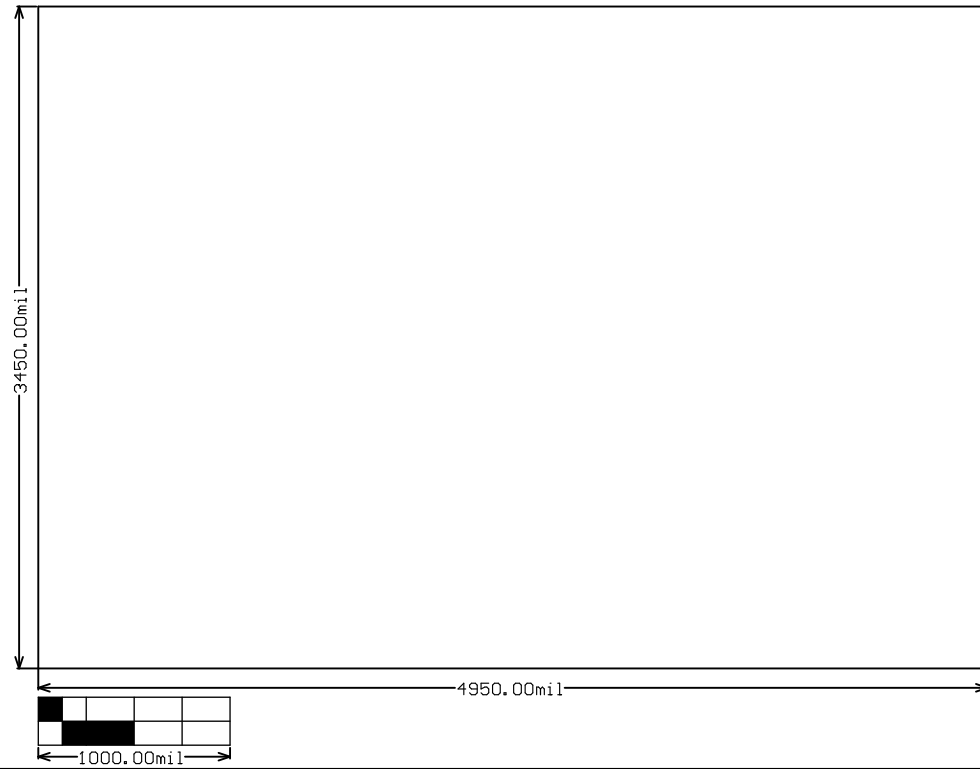


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01574	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01574		
PLOT NAME = Bottom Overlay	GENERATED : 12/15/2017 12:21:17 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	1	77.95mil (1.980mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	18	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	20	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	81	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
□	12	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
	140 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01574	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01574		
PLOT NAME = Drill Drawing	GENERATED : 12/15/2017 12:21:18 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01574	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01574		
PLOT NAME = Board Dimensions	GENERATED : 12/15/2017 12:21:20 AM	TEXAS INSTRUMENTS	



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